[Press Release]

ASMPT enabling the digital world

ASMPT Announces 2026 Interim Results

Multiple Advanced Packaging Solutions Drive Strong Performance

Group Performance at a Glance

Key Highlights

- **AI continued to fuel strong revenue and bookings**
- **Record bookings for SMT; SEMI AP bookings doubled YoY**
- **Strong Group revenue growth driven by mainstream and Photonics**
- **Higher Group adjusted gross margin driven by SMT**
- **Revenue and adjusted EPS beat consensus**

Group Results Summary

(in HK$ million)	Q2 2026	QoQ	YoY	1H 2026	HoH	YoY
	Continuing Operations					
Bookings	7,080.4 (US$903.6 million)	+24.8%	+97.6%	12,753.8 (US$1,630.6 million)	+68.1%	+85.1%
Revenue	4,935.8 (US$630.0 million)	+24.4%	+52.1%	8,902.6 (US$1,138.0 million)	+18.9%	+42.5%
Gross Margin	42.4%	+292bps	+284bps	41.1%	+542bps	+86bps
Operating Profit	786.5	+104.2%	+300.1%	1,171.7	+384.9%	+205.2%
Net Profit	417.8	+29.0%	+177.1%	741.6	-9.9%	+183.8%
Basic earnings per share	HK$1.01	+29.5%	+188.6%	HK$1.79	-9.6%	+188.7%
	Non-HKFRS Measures[1] of Continuing Operations					
Adjusted Gross Margin	42.5%	+302bps	+284bps	41.2%	+441bps	+86bps
Adjusted Operating Profit	847.0	+114.1%	+268.8%	1,242.6	+220.9%	+195.6%
Adjusted Net Profit	637.5	+90.2%	+253.9%	972.7	+263.8%	+230.5%
Adjusted Basic earnings per share	HK$1.53	+88.9%	+255.8%	HK$2.34	+260.0%	+234.3%

(in HK$ million)	Q2 2026	QoQ	YoY	1H 2026	HoH	YoY
	Discontinued[2] Operation					
Net Loss	(85.6)	+17.9%	+419.9%	(158.2)	+14.3%	+256.0%
Adjusted Net Loss (Non-HKFRS Measures[1])	(94.2)	+29.8%	+486.4%	(166.8)	NM	+279.1%

NM: Not meaningful

(in HK$ million)	Q2 2026	QoQ	YoY	1H 2026	HoH	YoY
	Continuing and Discontinued[2] Operations					
Net Profit	332.3	+32.3%	+147.3%	583.5	-14.8%	+169.0%
Basic Earnings Per Share	HK$0.80	+31.1%	+150.0%	HK$1.41	-14.5%	+171.2%
	Non-HKFRS Measures[1] of Continuing and Discontinued[2] Operations					
Adjusted Net Profit	543.3	+106.9%	+231.2%	806.0	+132.1%	+221.9%
Adjusted Basic Earnings Per Share	HK$1.31	+104.7%	+235.9%	HK$1.94	+131.0%	+223.3%

Revenue Guidance for Q3 2026

- US$630 million to US$690 million, +4.8% QoQ and +46.3% YoY at mid-point

Full Results Announcement and Investor Presentation available from
https://www.asmpt.com/en/investor-relations/financial-information/

1 For more information about the Non-HKFRS Measures presented above, please refer to the section under "Reconciliation of HKFRS Measures to the non-HKFRS Measures" of the Group's Q2 2026 results announcement.

2 The Closing of the Disposal of ASMPT NEXX, Inc. ("NEXX") took place on 3 June 2026 in accordance with the terms of the SPA. Following Closing, NEXX has ceased to be a subsidiary of the Company, with its financial results no longer being consolidated into the Group's consolidated financial statements.

(Hong Kong, 29 July 2026) — **ASMPT Limited** (ASMPT / the Group / the Company) (Stock code: 0522), a leading global provider of hardware and software solutions for the manufacture of semiconductors and electronics, announced its interim results for the six months ended 30 June 2026.

"We delivered a strong first half 2026 performance, with Q2 revenue and EPS above consensus and robust bookings momentum, as multiple ASMPT products benefitted from a combination of structurally driven AI demand and recovery in some traditional mainstream applications," said **Mr. Robin Ng, Group CEO**. "Looking ahead, despite longer lead times for some materials, our long term demand trajectory remains intact. With our strong product portfolio and technology leadership, we are confident of sustained growth for 2026."

Group 1H 2026 Highlights

The advancement of AI capabilities continued to place increasing demands on semiconductor manufacturing beyond compute capabilities, benefitting both the Group's Advanced Packaging (AP) and mainstream solutions. Its AP business delivered a record half-year performance, driven by robust demand across Thermo-Compression Bonding (TCB), Photonics and high-precision SMT solutions. In parallel, AI infrastructure buildouts contributed to the Group's mainstream business for both SEMI and SMT. Looking beyond AI, the Group's mainstream business also experienced some recovery from traditional applications such as consumer, industrial and automotive EVs.

- Revenue from Continuing operations was HK$8.90 billion (US$1.14 billion), up 18.9% HoH and 42.5% YoY. Both SEMI and SMT registered strong revenue growth due to AI tailwinds.

- Bookings were HK$12.75 billion (US$1.63 billion), increased 68.1% HoH and 85.1% YoY;
- SEMI bookings registered strong growth of 56.9% HoH and 81.9% YoY while SMT bookings were up significantly by 78.6% HoH and 87.8% YoY. The Group achieved a book-to-bill ratio of 1.43, the highest since 1H 2021.
- Adjusted gross margin was 41.2%, up 441 bps HoH and 86 bps YoY, driven by higher gross margin from both SMT and SEMI.
- Adjusted operating expenditure (OPEX) was HK$2.42 billion, up 2.4% HoH due to higher volume and 15.4% YoY, mainly driven by higher volume, unfavourable FX impact, merit increases, and strategic infrastructure and R&D investments.
- Adjusted operating profit of HK$1.24 billion, up significantly by 220.9% HoH and 195.6% YoY due to gross margin improvement and operating leverage.
- Adjusted net profit up 263.8% HoH and 230.5% YoY to HK$972.7 million, due to higher operating profit.
- Maintained a robust balance sheet with healthy cash and bank deposits of HK$5.88 billion, net cash at HK$3.63 billion.
- The Board of Directors has declared an interim dividend of HK$0.97 per share.

Advanced Packaging – Robust AP Growth and Expanding Opportunities
The AP business's record half-year revenue was US$339.0 million in 1H 2026, up 17% YoY increase and accounting for 30% of Group revenue. TCB, SMT high precision and Photonics solutions were the largest contributors within the AP portfolio. The Group's AP solutions are becoming key enablers for present and future AI infrastructure.

TCB: In logic, order momentum for the Group's Chip-to-Substrate (C2S) solutions remained strong, supported by repeat orders for larger compound die TCB tools from OSAT partners of the leading advanced logic customer. Notably, in July 2026 the Group received new bulk orders for more than 50 of its C2S TCB tools from OSAT customers. The Group's comprehensive C2S portfolio is supporting the industry's transition to larger compound dies for higher AI workloads, further reinforcing its leadership in C2S applications. For Chip-to-Wafer (C2W), the Group secured a bulk order from a leading global integrated device manufacturer (IDM) for advanced CPUs to support client computing and AI inferencing. It also delivered ultrafine pitch TCB tools to the leading advanced logic customer, underscoring its strong position in C2W applications.

In memory, even as the Group continued to secure repeat orders from HBM manufacturers, the timing of customers' new tool purchase decisions remains dependent on HBM4 product rollout schedules. The Group also entered into an exclusive joint evaluation programme with a key memory player to establish its technology as a preferred production standard.

In other TCB developments, panel-level packaging is emerging as a potential growth driver for the Group. It shipped its newly developed chip-on-panel tool to the leading customer for qualification and is collaborating with leading industry players to develop packaging solutions for both embedded and surface silicon bridges.

Photonics: Pluggable Optical Transceiver solutions revenue almost tripled YoY, driven by customer capacity ramps for high-speed optical transceivers for 800G and beyond. In Co-Packaged Optics (CPO), the Group strengthened its collaboration with multiple leading global players, positioning itself strongly to capture market share as CPO adoption accelerates. The Group offers the industry's broadest portfolio of CPO solutions, spanning ultra-high precision photonics, TCB and hybrid bonding (HB).

Flip Chip High Precision Die-Bonding (FC): FC’s revenue registered strong growth for customers that require high-throughput, large-format applications, and cost efficiency. These are deployed for 2.5D AI package, and panel-level fan-out applications for radio frequency and power devices.

HB: The Group’s second-generation HB platform continued to gain traction, delivering competitive alignment precision, bonding accuracy, footprint efficiency, and UPH. Active collaboration with key logic and memory customers has progressed to the sampling stage, an important step toward potential qualification.

SEMI Mainstream: SEMI’s mainstream business saw substantial growth, backed by high utilisation at leading IDMs amid improving demand for power management requirement for AI data centres and industrial applications. In particular, both revenue and bookings in China were especially strong, with demand for wire bonding and die bonding tools driven by continued AI infrastructure expansion and high OSAT utilisation.

SMT: SMT delivered record bookings in Q2 and 1H 2026, with AI servers continuing to be a significant source of demand, supported by the accelerated adoption of SMT’s high flex, high force solutions for large format board assembly. Bookings growth was also underpinned by demand for optical transceivers and China's EV segment.

Group Q2 Financial Highlights

- Revenue came in at HK$4.94 billion (US$630.0 million), exceeding the upper end of the Group’s guidance, up 24.4% QoQ and 52.1% YoY, driven by both SEMI and SMT.
- Bookings was HK$7.08 billion (US$903.6 million), up 24.8% QoQ and 97.6% YoY, significantly better than anticipated for both SEMI and SMT.
- Adjusted gross margin was 42.5%, up 302 bps QoQ and 284 bps YoY, coming from both SMT and SEMI.

- Adjusted operating profit was HK$847.0 million, up 114.1% QoQ and 268.8% YoY due to higher gross margin and operating leverage.
- Adjusted net profit of HK$637.5 million, up 90.2% QoQ and 253.9% YoY due to higher operating profit.

Outlook

The Group expects Q3 2026 revenue to be between US$630 million and US$690 million, up 4.8% QoQ and 46.3% YoY at mid-point, and above market consensus despite longer lead times for certain materials.

The Group expects Q3 2026 bookings to grow by a high single-digit percentage sequentially, mainly driven by TCB and Photonics.

The proliferation of AI will continue to drive structural demand for advanced AI applications and computing needs, benefitting the Group's products - from AP solutions that are able to address complex technical requirements across the AI value chain, to mainstream solutions that can support the demands of extensive AI infrastructure buildouts. Turning to mainstream, the Group believes that the recovery of demand for some traditional applications will continue. The Group remains confident of revenue growth across both SEMI and SMT in 2026 despite longer lead times as mentioned above, and customers' dynamic AI product rollout schedules.

- End –

ASMPT Limited
29 July 2026

For media enquiries:

Lim Ee Guan
Director, Corporate Communications
Tel: +65 6450 1445
Email: eg.lim@asmpt.com

On behalf of ASMPT:

Strategic Financial Relations Limited
Mandy Go / Vivienne Leung / Angela Shen
Tel: +852 2864 4812 / 2864 4862 / 2864 4870
Fax: +852 2527 1196

Email: mandy.go@sprg.com.hk / vivienne.leung@sprg.com.hk / angela.shen@sprg.com.hk